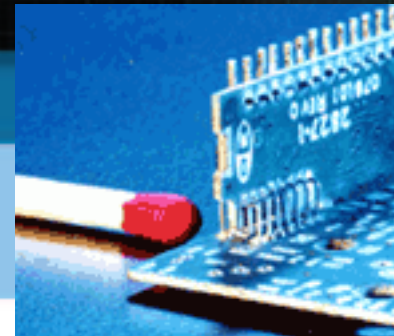


DIGI-KLIP® SMP/SMA Series

Micro-Miniature, Single Row, Free-Standing Card Edge Contacts



Home

>>Products

>>Through Hole

Surface Mount

Custom Wireform

News

About Us

Distributor &
Representative
Search

Contact Us

Check Stock

Compliance

Site Map

Specifications

- ❑ **SMP050/SMA050:** .050" centerline spacing, maximum of 50 contacts per carrier strip.
- ❑ **SMP100/SMA100:** .100" centerline spacing, maximum of 25 contacts per carrier strip.

Materials:

Contact Material: #172 alloy .012" diameter beryllium copper wire, heat treated after forming.

Mechanical:

Module Board Thickness: SMP = .031" +/- .004"
SMA = .062" +/- .005"

Carrier Strip Material: 30% glass filled polyester thermoplastic, disposable, available cut to length from four contacts to maximum available for series selected.

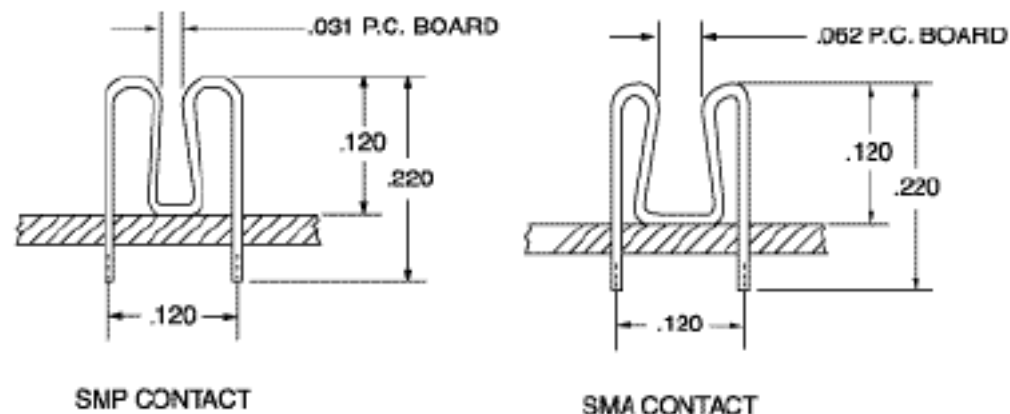
Mounting Holes: .018" diameter

Electrical:

Contact Resistance: Less than .005 ohm per contact.

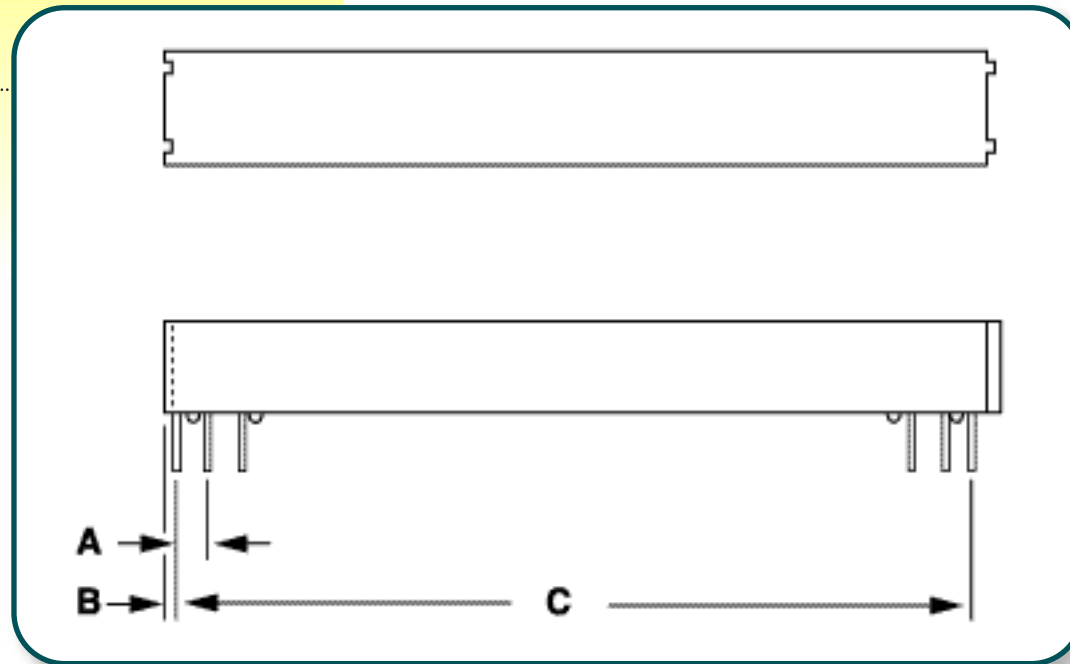
Maximum Current: 1.0 ampere per contact

SMP/SMA Contacts



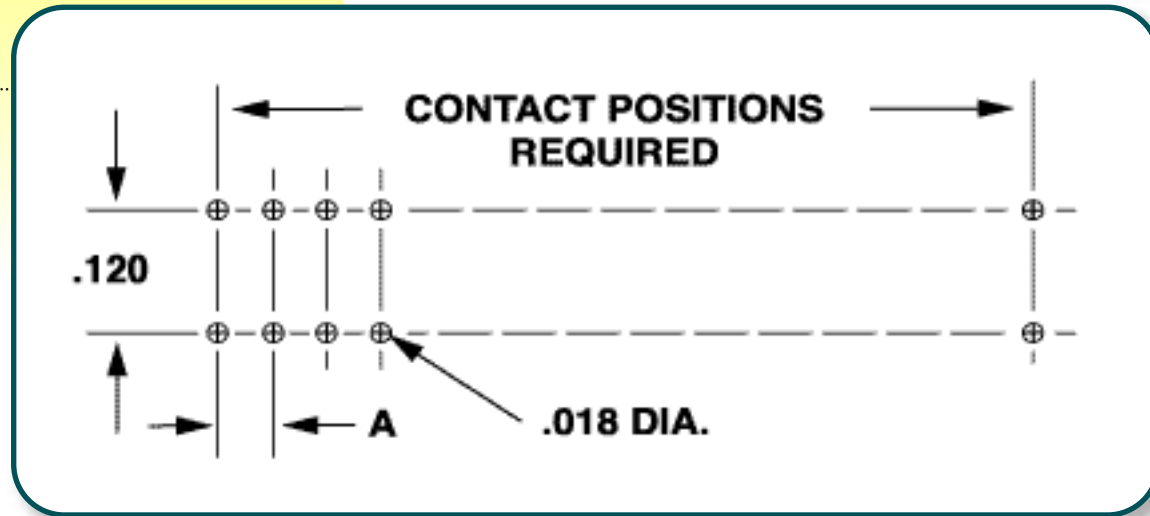
Click Here for
DIGI-KLIP®
High Performance
Data Information

SMP/SMA Carrier Strip



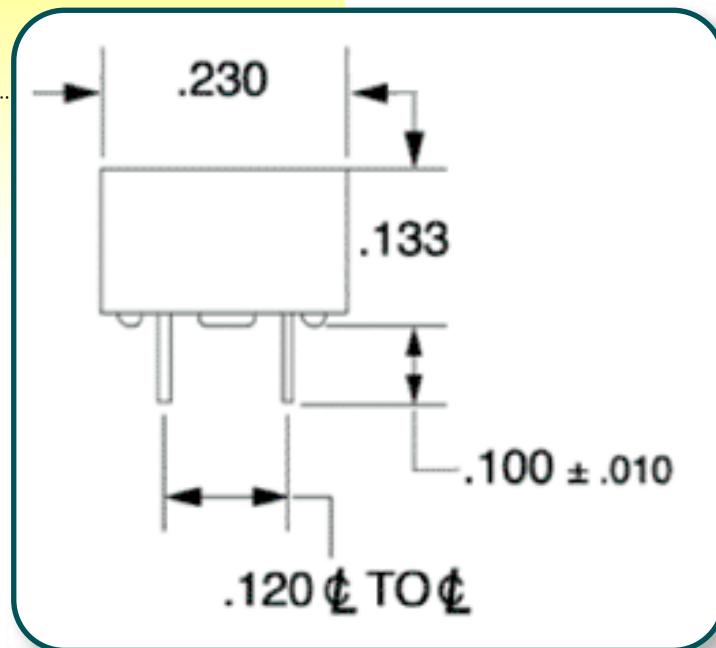
Series	A	B Maximum	C Contact Pairs
SMP050	.050	.025	4 thru 50
SMP100	.100	.050	4 thru 25
SMA050	.050	.025	4 thru 50
SMA100	.100	.050	4 thru 25

**SMP/SMA
Board Layout**



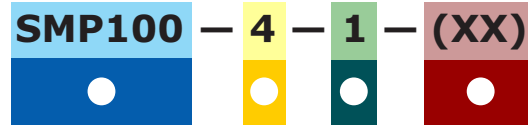
Series	Dim. A
SMP050	.050
SMP100	.100
SMA050	.050
SMA100	.100

**SMP/SMA
Accessories**



Ordering Information

Example



Series Designation:
SMP = .031" Printed Circuit Board
SMA = .062" Printed Circuit Board

Contact Spacing:
050 = .050"
100 = .100"

Contacts:
SMP050 = 4 thru 50 Contacts
SMA050 = 4 thru 50 Contacts
SMP100 = 4 thru 25 Contacts
SMA100 = 4 thru 25 Contacts

Contact Plating Code:
1 = .0001" Electro Tin over Copper
2 = .00003 Gold over Nickel*
3 = .00005" Gold over Nickel*
4 = .0001" Nickel

Custom Design (Optional):
Assigned by factory for special configuration.

*All gold finishes per
MIL-G-45204

Product Description

The DIGI-KLIP® SMP/SMA Series, micro-miniature free-standing card edge interconnect system provides the lowest profile and highest density available for the card edge interconnect of two printed circuit boards.

The unique wireform contacts are manufactured from annealed beryllium copper alloy and heat treated after forming for spring temper. The proprietary concept produces free-standing card edge contacts which exhibit superior stress relaxation characteristics, a "wiping action," "gas tight" junction and low contact resistance.

Whether the SMP series (for .031" mating board) or the SMA Series (for .062" mating board) is selected, significant space savings may be achieved. Both contact styles have an above board height of .120" and require mounting holes of only .120" centers.

Choice of adjacent contact spacing is .050" for the SMP050 or SMA050 and .100" for the SMP100 and SMA100 Series. Any combination of single row contacts may be provided from 4 through 50 (SMP050/SMA050) or 4 through 25 (SMP100/SMA100), on convenient, disposable carrier strips.

Although designed for single row application, the contact geometry of the SMP/SMA Series provides dual path potential for further contact integrity.

Certificate of Compliance with Directive 2002/95/EC RoHS

This is to certify that Components Corporation designs, manufactures and supplies products to our customers that are in compliance with directive 2002/95/EC. This also pertains to procurement of raw material, component parts and processes.



Top
of Page

[Open this page as a PDF document](#)

Components Corporation

6 Kinsey Place Denville, NJ 07834 USA

voice: 866.4.COMPCO **fax:** 973.361.5801 **email:** sales@componentscorp.com

©2003 Components Corporation. All Rights Reserved. [Legal Statement](#). [Privacy Notice](#).